Thermally Conductive Products

Thermiflex® TF 21061

Properties: Thermiflex® TF 21061 has a smooth texture as well as high thermal conductivity and electrical insulation.

Characteristics: Due to the high thermal conductivity and electrical insulation, the thermal resistance of Thermiflex® TF 21061 can be optimized at low pressure. The smooth surface structure maximizes the thermal performance.

Application: Thermiflex® TF 21061 was designed for low cost applications, where a high thermal performance is required. These applications usually have low assembly pressure when fixing onto components. Applications where low clamping force is necessary include discrete semiconductors (TO-220, TO-247 and TO-218), which are attached with spring clips. Spring clips allow for quick installation, however only a limited amount of pressure is applied on the semiconductor.

Colour: Thermiflex® TF 21061 is available in gold colour as standard.

Stand November 2014

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**Thermiflex® TF 21061**

**Storage Conditions:** Thermiflex® TF 21061 should be stored in dry conditions, at room temperature and in the original packaging.

**Form of Supply:** Thermiflex® TF 21061 is supplied in rolls and in sheet form as well as customer specified stamped parts on request.

<table>
<thead>
<tr>
<th>Properties</th>
<th>Norm</th>
<th>Unit</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Total Thickness</td>
<td>-</td>
<td>mm</td>
<td>0.13</td>
</tr>
<tr>
<td>Colour</td>
<td>-</td>
<td>-</td>
<td>gold</td>
</tr>
<tr>
<td>Hardness</td>
<td>ASTM D2240</td>
<td>Shore A</td>
<td>85</td>
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<tr>
<td>Density</td>
<td>ASTM D792</td>
<td>g/cm³</td>
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<tr>
<td>Tensile Strength</td>
<td>ASTM D412</td>
<td>N/mm²</td>
<td>83</td>
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<tr>
<td>Elongation</td>
<td>ASTM D412</td>
<td>%</td>
<td>20</td>
</tr>
<tr>
<td>Thermal Sheet Resistance</td>
<td>-</td>
<td>K mm²/W</td>
<td>81</td>
</tr>
<tr>
<td>Specific Electrical Resistance</td>
<td>-</td>
<td>Ω · m</td>
<td>10⁻⁵</td>
</tr>
<tr>
<td>Dielectric Strength</td>
<td>ASTM D149</td>
<td>Kv/mm</td>
<td>≥3.0</td>
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<tr>
<td>Thermal Conductivity</td>
<td>ASTM E1461</td>
<td>W/m.k</td>
<td>1.6</td>
</tr>
</tbody>
</table>

**Trademark Information:** Thermiflex® is a registered trademark of the company Dr. Dietrich Müller GmbH, Germany.
Please note: The information in this data sheet is based on our current knowledge and experience. They do not disengage the fabricator and user from own tests and inspections because of the plenty of possible effects. There is no judicial binding assurance of certain properties or of the qualification for a concrete application in our declaration. We recommend consulting us in individual cases. The acceptor of our products has to observe possible industrial property rights as well as present laws by himself.